



# ACE14409T

## P-Channel Enhancement Mode Field Effect Transistor

### Description

The ACE14409T uses advanced trench technology to provide excellent  $R_{DS(ON)}$  with low gate charge. It can be used in a wide variety of applications.

### Features

- $V_{DS}(V)=-30V$
- $I_D=-12A$
- $R_{DS(ON)} < 12m\Omega$  ( $V_{GS}=-10V$ )
- $R_{DS(ON)} < 18m\Omega$  ( $V_{GS}=-4.5V$ )

### Absolute Maximum Ratings

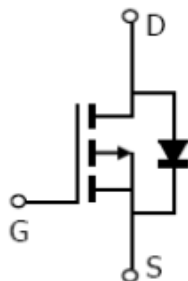
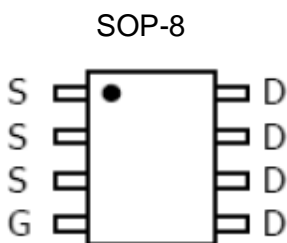
Parameter	Symbol	Max	Unit
Drain-Source Voltage	$V_{DS}$	-30	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current (Continuous) * AC	$I_D$	$T_A=25^\circ C$	-12
		$T_A=100^\circ C$	-7.5
Drain Current (Pulse) * B	$I_{DM}$	-48	A
Power Dissipation	$P_D$	$T_A=25^\circ C$	3
		$T_A=100^\circ C$	1.8
Operating and Storage Temperature Range	$T_J, T_{STG}$	-55 to 150	$^\circ C$

A: The value of  $R_{\theta JA}$  is measured with the device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with  $T_A=25^\circ C$ . The value in any given application depends on the user's specific board design.

B: Repetitive rating, pulse width limited by junction temperature.

C: The current rating is based on the  $t \leq 10s$  junction to ambient thermal resistance rating.

### Packaging Type



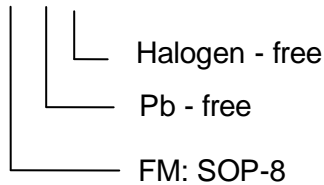


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### Ordering information

ACE14409T XX + H



### Electrical Characteristics

$T_A=25\text{ }^\circ\text{C}$  unless otherwise noted

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=-250\mu A$	-30			V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=-30V, V_{GS}=0V$			-1	$\mu A$
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_{DS}=-250\mu A$	-1	-1.5	-3	V
Gate Leakage Current	$I_{GSS}$	$V_{GS}=\pm 20V, V_{DS}=0V$			$\pm 100$	nA
Static Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=-10V, I_D=-10A$		12	15	m $\Omega$
		$V_{GS}=-4.5V, I_D=-7A$		18	25	
Forward Transconductance	$g_{FS}$	$V_{GS}=-10V, I_D=-10A$	20			S
Diode Forward Voltage	$V_{SD}$	$I_{SD}=-2A, V_{GS}=0V$			-1.2	V
Switching						
Total Gate Charge	$Q_g$	$V_{GS}=-10V, V_{DS}=-15V, I_D=-10A,$		24		nC
Gate-Source Charge	$Q_{gs}$			3.5		
Gate-Drain Charge	$Q_{gd}$			6		
Turn-On Delay Time	$T_{d(on)}$	$V_{GS}=-10V, V_{DS}=-15V, I_D=-10A, R_{GEN}=1\Omega$		9		ns
Turn-On Rise Time	$t_f$			8		
Turn-Off Delay Time	$t_{d(off)}$			28		
Turn-Off Fall Time	$t_f$			10		
Dynamic						
Input Capacitance	$C_{iss}$	$V_{GS}=0V, V_{DS}=-15V, f=1MHz$		1750		pF
Output Capacitance	$C_{oss}$			215		
Reverse Transfer Capacitance	$C_{rss}$			180		



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### Typical Performance Characteristics

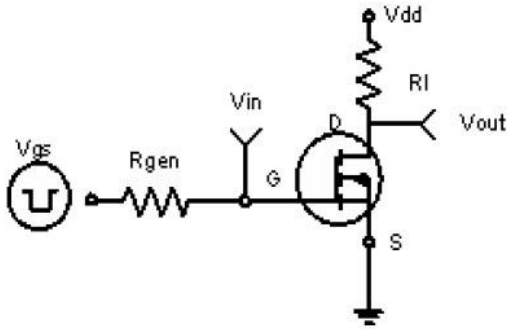


Figure 1: Switching Test Circuit

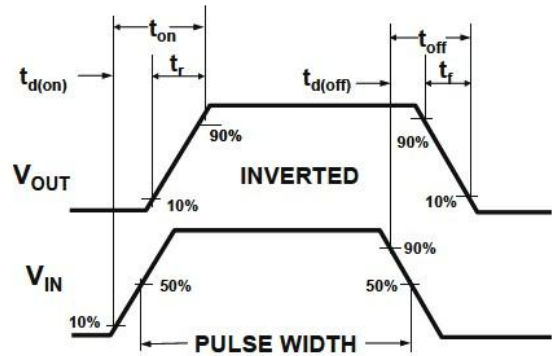


Figure 2: Switching Waveforms

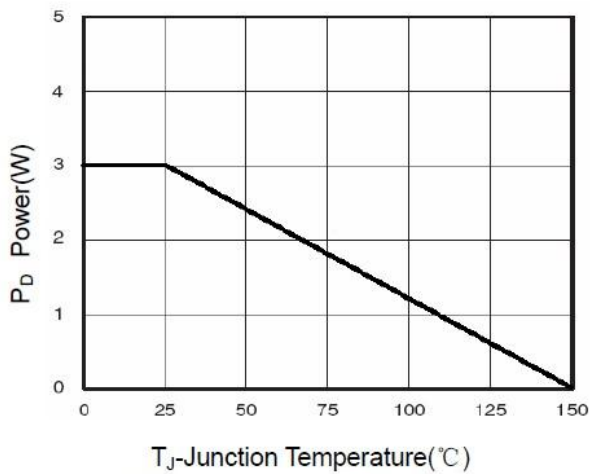


Figure 3 Power Dissipation

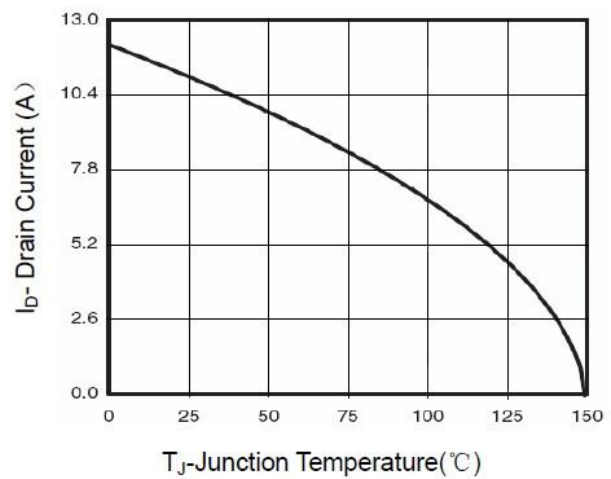


Figure 4 Drain Current

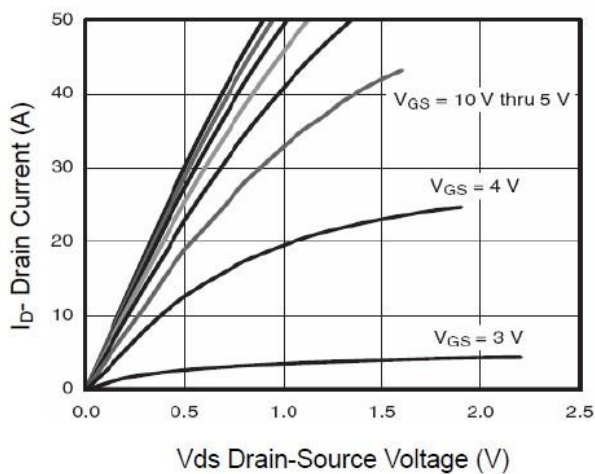


Figure 5 Output Characteristics

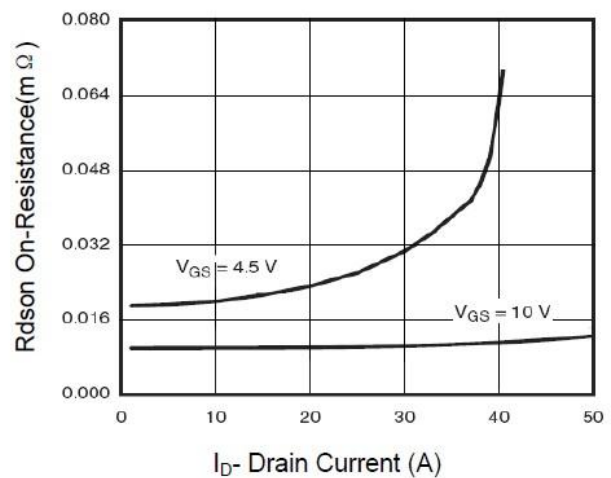


Figure 6 Drain-Source On-Resistance



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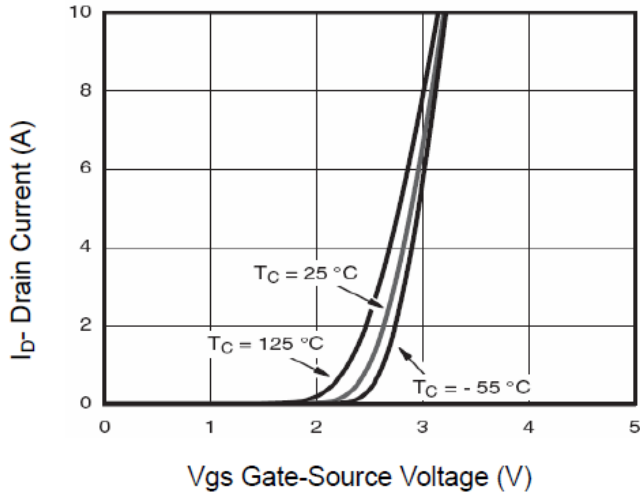


Figure 7 Transfer Characteristics

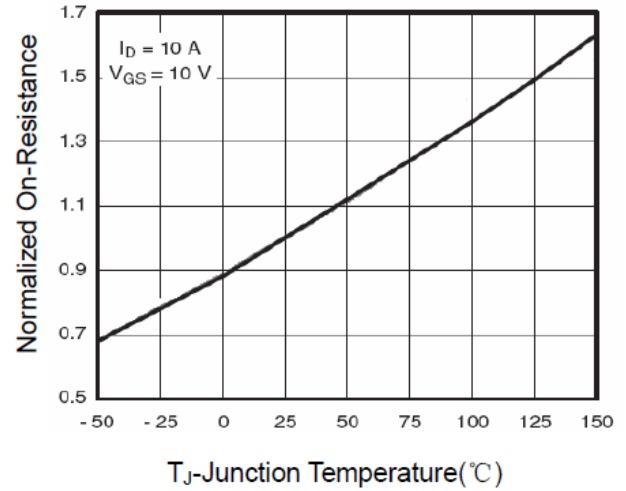


Figure 8 Drain-Source On-Resistance

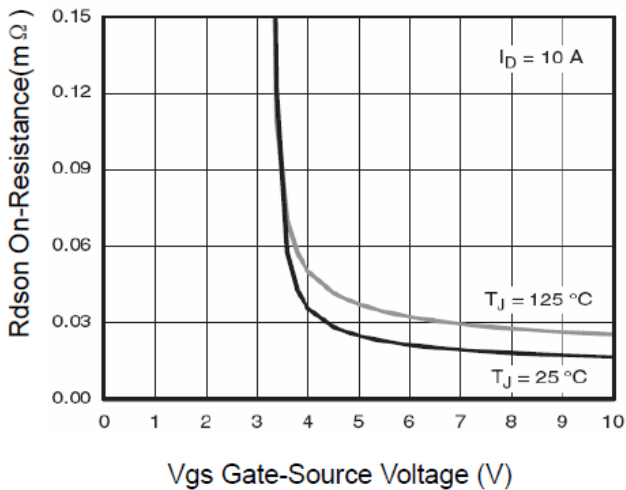


Figure 9  $R_{DS(on)}$  vs  $V_{GS}$

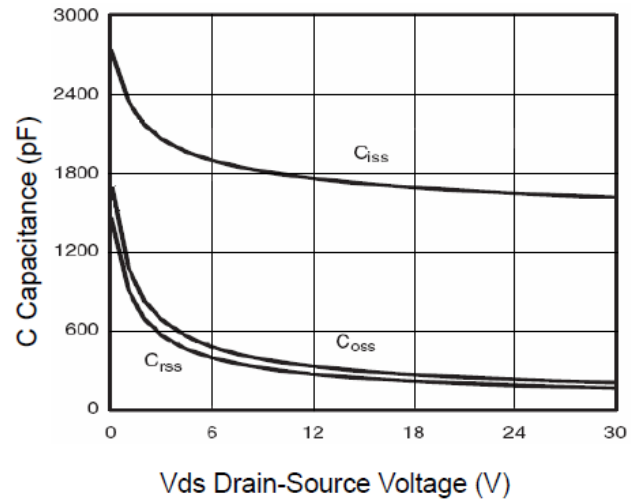


Figure 10 Capacitance vs  $V_{DS}$

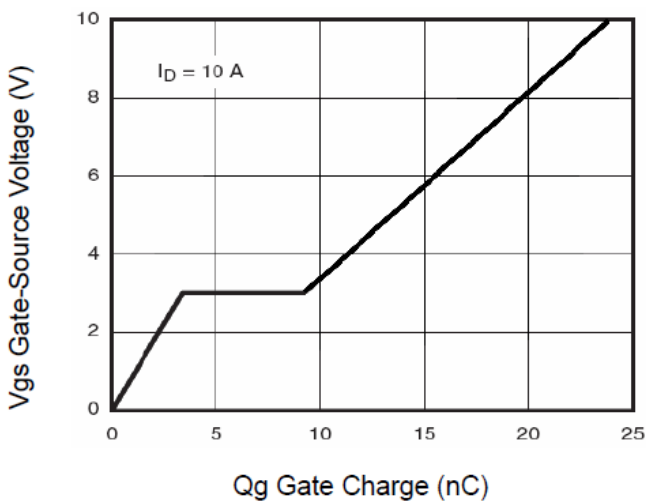


Figure 11 Gate Charge

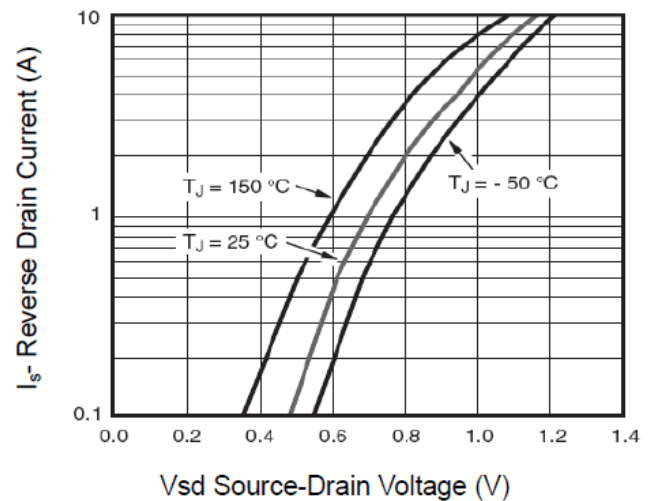


Figure 12 Source-Drain Diode Forward



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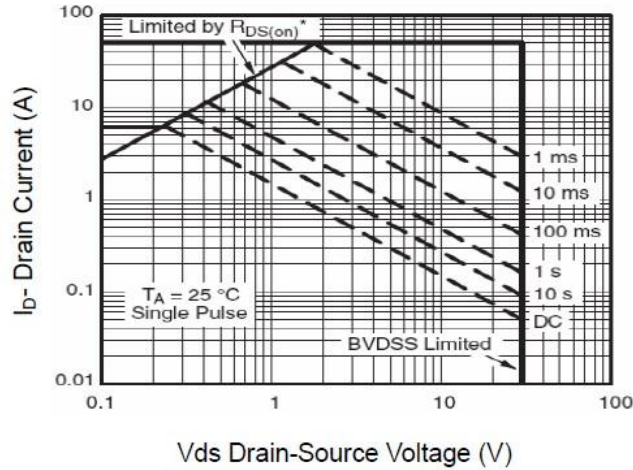


Figure 13 Safe Operation Area

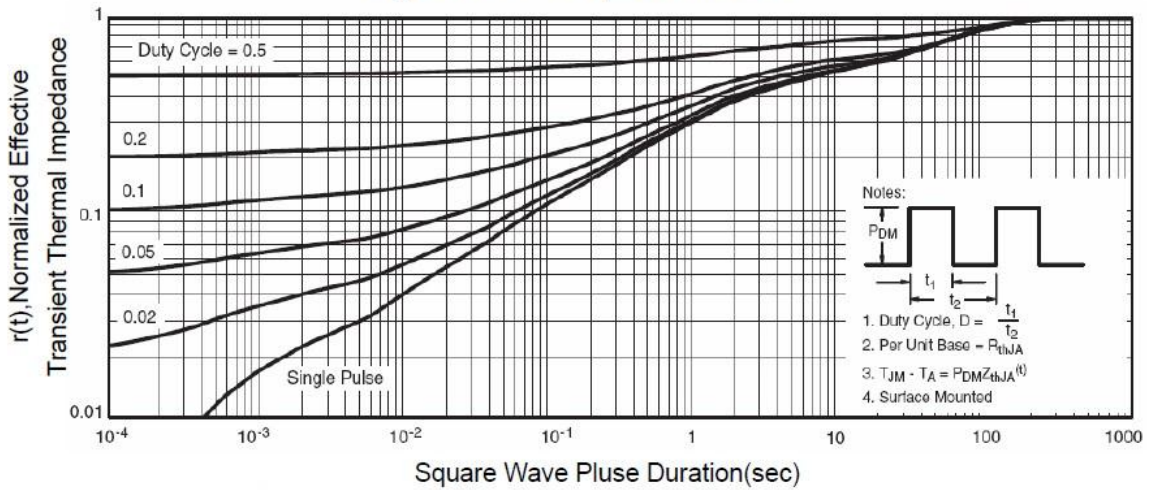


Figure 14 Normalized Maximum Transient Thermal Impedance

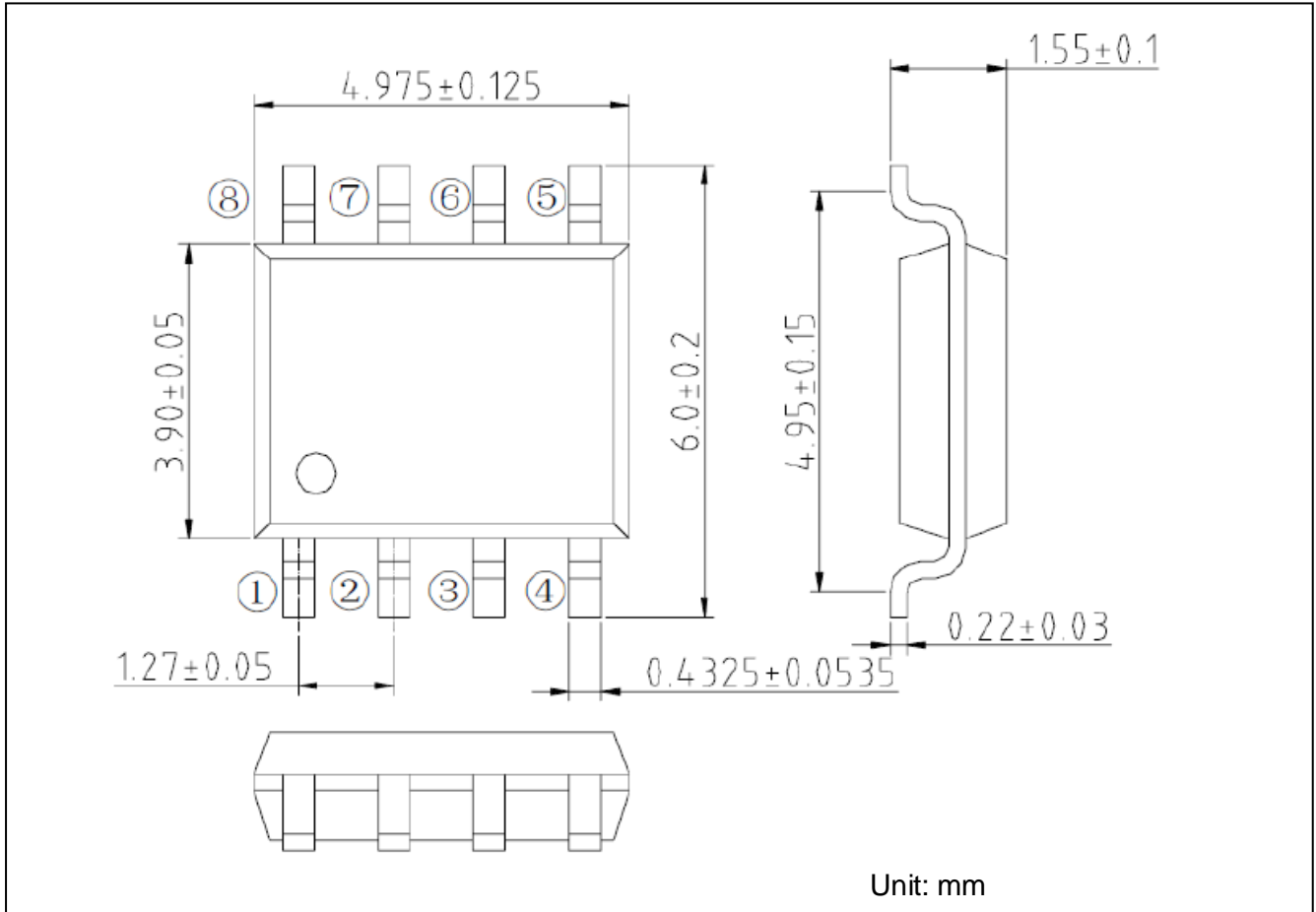


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### Packing Information

#### SOP-8





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### Notes

ACE does not assume any responsibility for use as critical components in life support devices or systems without the express written approval of the president and general counsel of ACE Electronics Co., LTD. As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury to the user.
2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.